IPC ASSOCIATION OF ELECTRONICS	Material Co © Copyright 20 international an	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.				This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lowe level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.								
752-21.1		IPC Web Site for Information on IPC-1752 Standard http://www.ipc.org/IPC-175x Form Type Distribute				* Declaration Class * Class 6 - RoHS Yes/No. Homogeneous Materi				ials and Mfg Information				
upplier l	Information											_		
Company name* Company unique ID				nique ID	.D Unique II		que ID Authority				Response Date*			
onsemi											2025-06-09			
Contact Name T				Title - Contact			Phone - Contact*				Email - Contact*			
?roduct-En	nv-Stewards		Product Env	Product Enviro Compliance			NA				Product-Env-Stewards@onsemi.com			
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roduct-En	nv-Stewards		Product Env	Product Enviro Compliance			NA				Product-Env-Stewards@onsemi.com			
	Requester Item Number M		Mfr Item Number Mfr Item Name			Effe		Version	Manu	Manufacturing Site		Weight*	UOM	Unit Type
		NTP125N60S5FZ SuperFET		SuperFET5 FRFET	FRFET, 125mohm, TO-220-3		2025-06-09 CPA			2	2033.34	mg	Each	
	turing Process Info		Tamainal Daga	Aller	-STD-020 MSL Ratin		Dools Duo oo	oss Dady Tam	mamatuma N	Acy Time at Dook	Tommonot	Niverb	on of Botlayy Cyc	alac
	Š ,		Terminal Base Alloy J-STD-02 CU Allov NA			ıg	0	C Process Body Temperature Max Time at C 30			seconds 3		er of Reflow Cyc	cies
	viatte 1111 (SII) - aimeaieu	ll'	CU Alloy	1	IA .				, 13	<u> </u>	secon	us [3		
Comments														
or more in	nformation regarding mat	erial composition	please refer t	o page 3										

RoHS Material Composition Declaration			Declaration Type *	Detailed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (100 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).										
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its keloardine shall encompass all such components. Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its paragraph. If the Company and the Supplier shall applier of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form. In the absence of such written agreement, the warranty rights and/or remedies of Supplier's Standard Terms and Conditions of Sale applicable to such part shall apply.										
RoHS Declaration * 4 - Item(s) does not contain RoHS restricted substance	s per the definition above except for selected exemp	tions Supplier Acceptance	* Accepted						
Exemption: 7a: Lead in high melting temperature type solders (i.e. lead based solder alloys containing 85% by weight or more lead).										
Exemption List Version	EL-2011/534/EU									
Declaration Signature										
Instructions: Complete all of the required fields on all pages of this form. Select the "Accepted" on the Supplier Acceptance drop-down. This will display the signature area. Digitally sign the declaration (if required by the Requester) and click on Submit Form to have the form returned to the Requester.										
Supplier Digital Signature Ra	astislav Drska	-En								

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	7.1	mg	Supplier	Silicon (Si)	7440-21-3		7.1	mg
Die Attach Solder	4.93		Supplier	Silver (Ag)	7440-22-4		0.1233	mg
			A	Lead (Pb)	7439-92-1	7a	4.5602	mg
			Supplier	Tin (Sn)	7440-31-5		0.2465	mg
Lead Frame	1492.12		В	Nickel (Ni)	7440-02-0		1.0445	mg
			Supplier	Iron (Fe)	7439-89-6		1.4921	mg
			Supplier	Copper (Cu)	7440-50-8		1489.1357	mg
			Supplier	Phosphorus (P)	7723-14-0		0.4476	mg
Mold Compound-Black	513.45			Epoxy resin	proprietary data		30.807	mg
			Supplier	Phenolic Resin	Proprietary Data		30.807	mg
			Supplier	Carbon Black (C)	1333-86-4		2.5673	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		436.4325	mg
			Supplier	Silica Crystalline (SiO2)	14808-60-7		12.8363	mg
Plating	13.3	mg	Supplier	Tin (Sn)	7440-31-5		13.3	mg
Wire Bond - Al	2.44	mg	Supplier	Aluminum (Al)	7429-90-5		2.44	mg